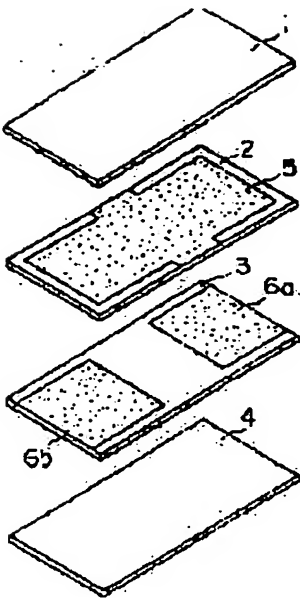


O-079



**(57)Abstract:**

**PURPOSE:** To improve the mounting density of a chip capacitor and to reduce mounting costs by arranging multiple first thick film electrodes, in the state separated each other, on one side across a substrate and arranging the second thick film electrode in the position corresponding to those first thick film electrodes on the other side.

**CONSTITUTION:** Of green sheets 1-4 obtained by printing and drying, by doctor blade method, a dielectric slurry on the base sheet of polyester, the dielectric slurry is printed and dried on the green sheets 2 and 3, and further, the dielectric paste is printed and dried by the doctor blade method so that a specified shape is obtained, thus, the second thick film electrode 5 and the first thick film electrodes 6a and 6b are formed. Of these thick film electrodes 5, 6a and 6b, capacitor elements 10 and 11 are formed in equivalent circuits of the thick film electrode pair 5 and 6a and the thick film electrode pair 5 and 6b, with the green sheet 2 in between.

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(54) MULTILAYERED CAPACITOR